

SAP

R&D

Semi-Additive Process

特長 Features

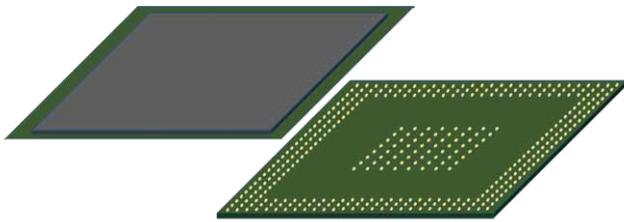
- 高精細パターン形成
High definition pattern formation

用途 Application

- FC-BGA パッケージ基板
FC-BGA package PCB

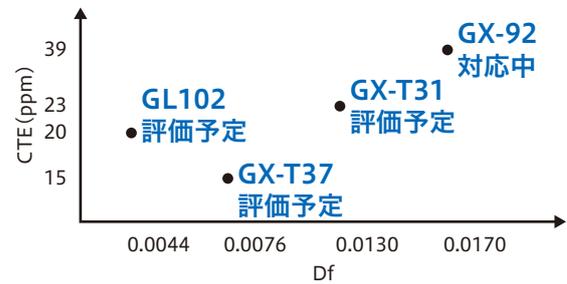
Package基板例 Package PCB

CPU基板 CPU PCB

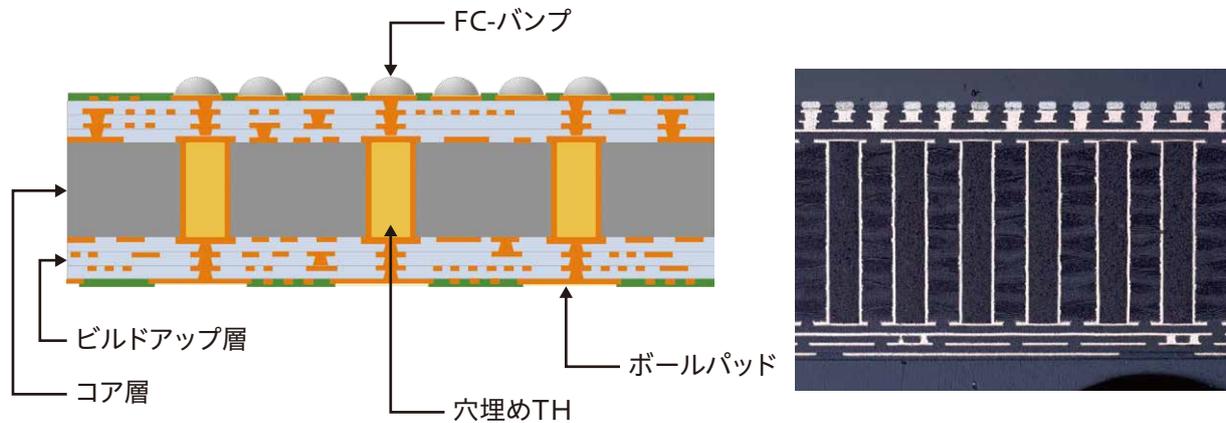


適用材料 Materials

ABF材 ABF material



構造事例 (断面図) Constructional Example (Cross Section)



パターン形成 Pattern formation

ABF layer
Target L/S = 10/10 μm

